Earnings Conference for FY2027/3 1Q

2026/08/04

TOKYO SEIMITSU CO., LTD.

KIMURA Ryuichi, President and CEO

KOIZUMI Kimito, Managing Executive Officer and CFO

TAKASHIMA Naoki, IR Team Leader, Management Support Dept.

Executive Summary

FY2027/3 1Q Results	• Company-wide orders totaled 65.8BJPY (up 83% year-over-year(YoY)), reaching a new quarterly high, with particularly strong growth in the SPE (up 102% YoY) • Revenue increased by 19% YoY, OP rose 29% year-over-year
Current Business Environment	• Strong demand for SPE continues • Metrology equipment segment also maintains a moderate growth trend • The production division remains busy and is considering additional investments to increase production capacity
FY2027/3 Forecast	• Revised FY Earnings Forecasts Based on Backlog and Business Environment (Sales: 181.5BJPY => 189.0BJPY; Operating Profit: 40.0BJPY => 44.0BJPY • Dividend projection updated following the Revision of Earnings (276JPY per share => 304JPY per share)

FY2027/3 1Q Quarterly Results

Company-wide sales and profits increased YoY, order reached record high (2Q sales and profits to increase QoQ)

Company-Wide results (BJPY)	FY2026/3 1Q	2Q	3Q	4Q	FY2027/3 1Q	QoQ	YoY
Orders	35.9	44.7	36.6	45.8	65.8	+44%	+83%
Sales	30.9	46.2	35.9	53.9	36.7	-32%	+19%
Operating profit (OP)	4.6	10.1	6.2	12.8	5.9	-54%	+29%
(OP Margin) (OPM)	(15%)	(22%)	(17%)	(24%)	(16%)	-8pt	+1pt
Recurring profit	4.5	10.5	6.7	13.1	6.4	-51%	+44%
Net profit	3.2	6.4	4.5	10.6	4.7	-56%	+45%
R&D	2.5	3.0	2.9	3.6	3.3	-6%	+34%
Capex	2.5	4.4	1.5	2.7	1.9	-28%	-23%
Depreciation	1.2	1.4	1.4	1.6	1.4	-5%	+17%

Segment Results		1Q	2Q	3Q	4Q	1Q	QoQ	YoY
SPE	Orders	26.4	34.9	26.0	36.1	53.2	+47%	+102%
	Sales	23.5	35.9	27.4	41.1	28.5	-31%	+21%
	OP	4.0	8.3	5.3	10.7	5.4	-50%	+34%
	(OPM)	(17%)	(23%)	(20%)	(26%)	(19%)	-7pt	+2pt
Metr.	Orders	9.5	9.8	10.7	9.7	12.6	+29%	+32%
	Sales	7.3	10.3	8.5	12.8	8.2	-36%	+12%
	OP	0.5	1.8	0.9	2.1	0.5	-75%	-7%
	(OPM)	(7%)	(18%)	(10%)	(16%)	(6%)	-10pt	-1pt

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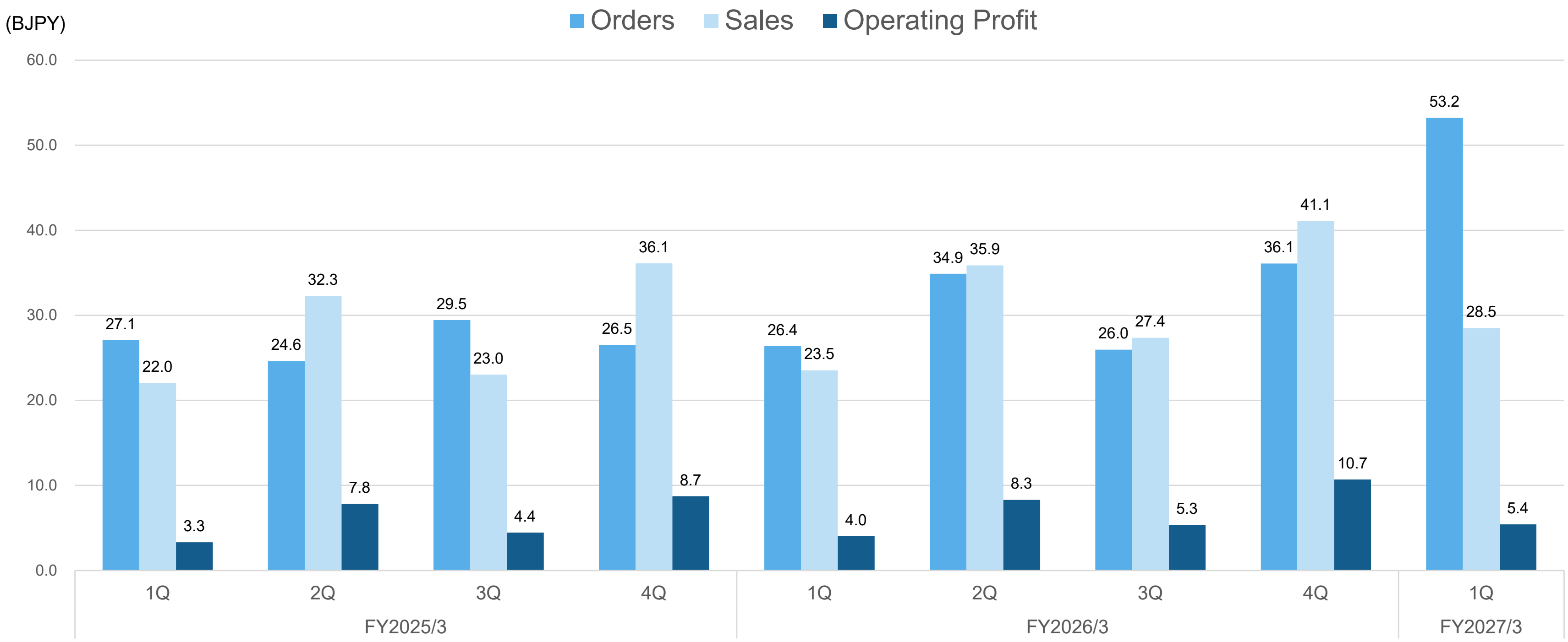
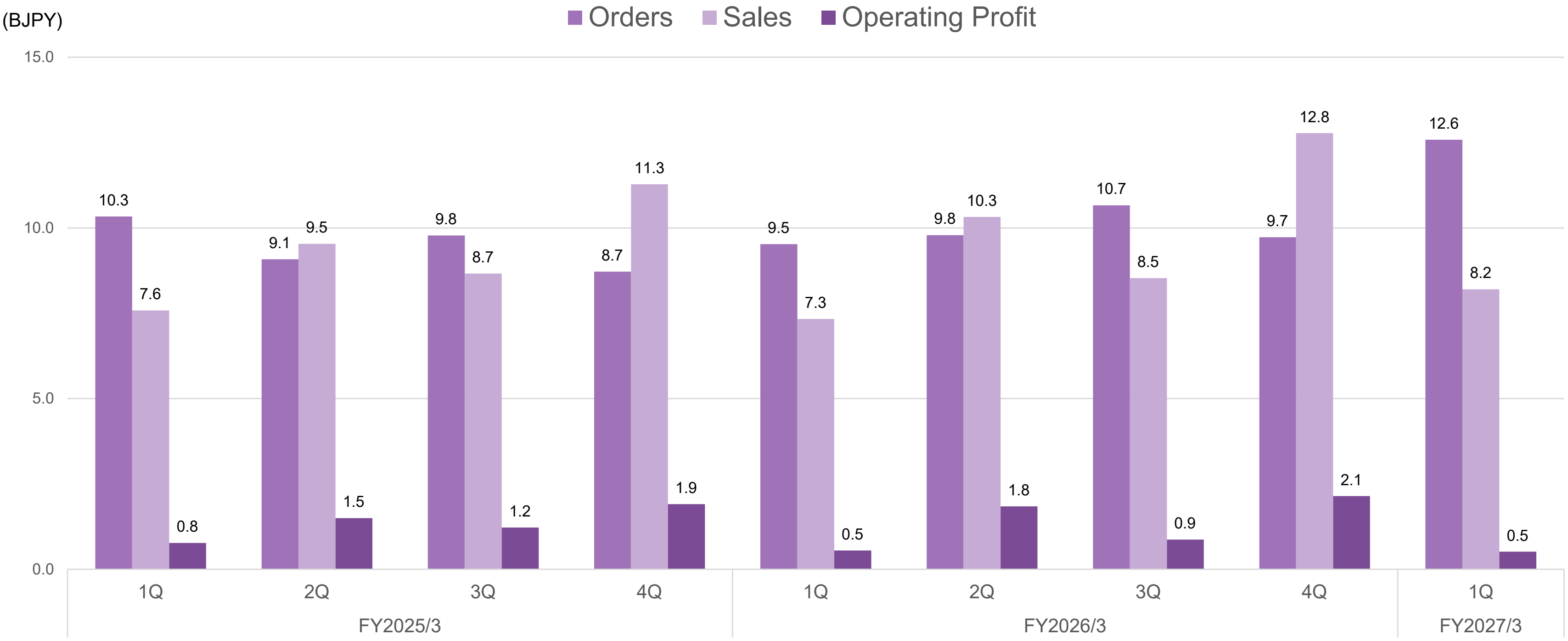
SPE Segment Quarterly Trend

1Q orders were well above expectations, driven by HPC (incl. gen AI) as well as strong demand from China and others



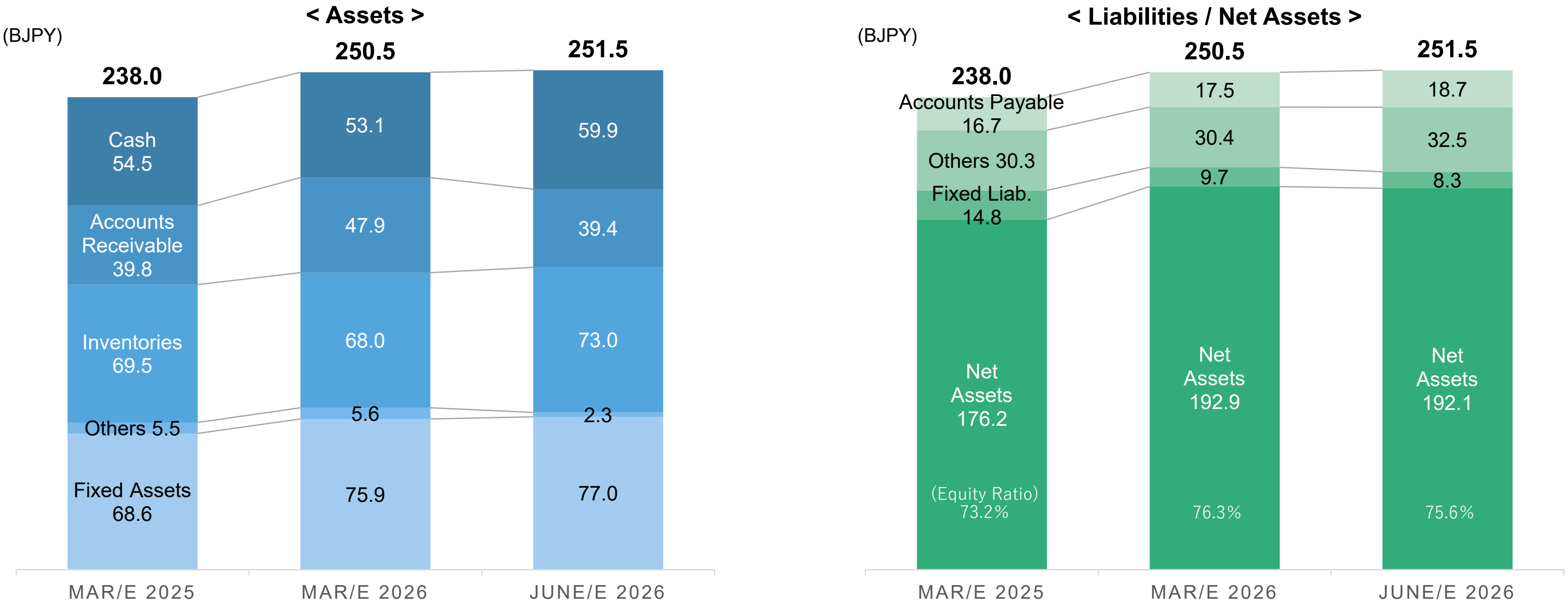
Metrology Segment Quarterly Trend

1Q orders at a high level thanks to additional investments for HV production, and AI data centers, robots, and others



Balance Sheet

Cash and cash equivalents and inventory increased compared to Mar/E



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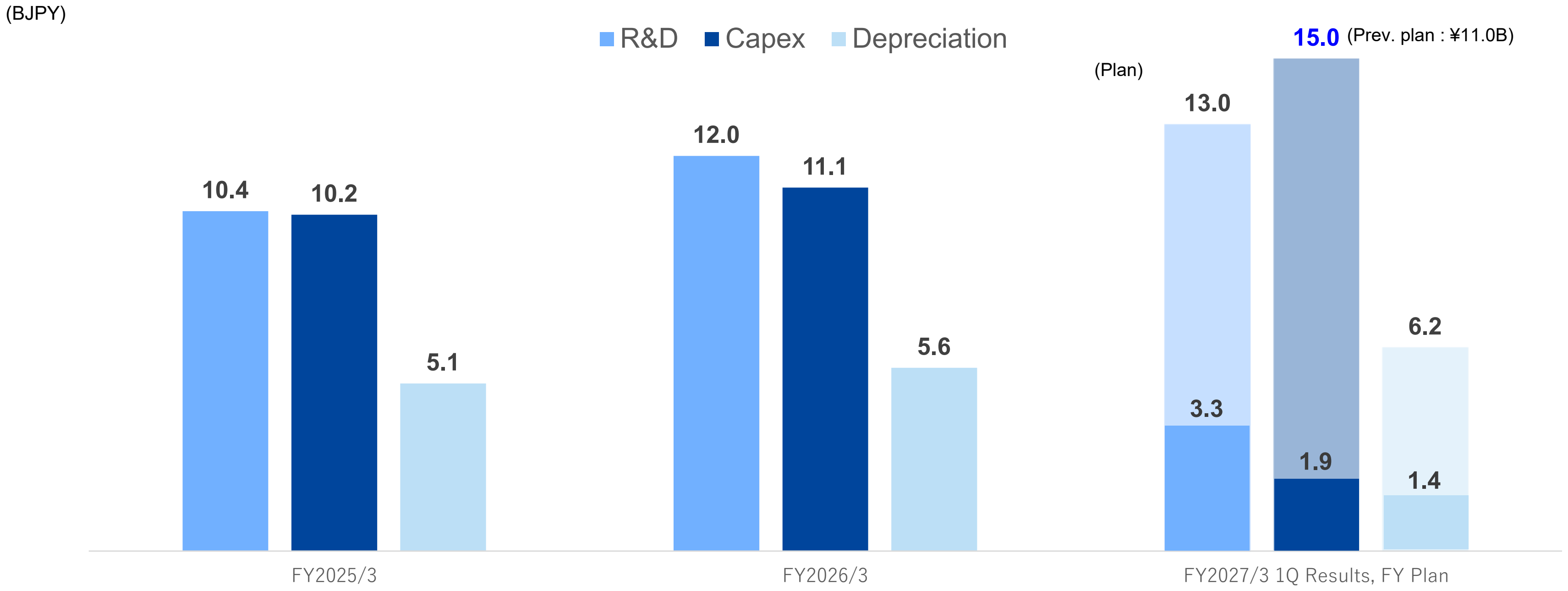
R&D, Capex and Depreciation

1Q results were generally in line with plans. The Capex plan was revised upward by ¥4.0B to increase capacity



Premises of FY2027/3 Forecast (Blue: changed by August)

Sales & Profits

SPE： Reflecting current demand, forecast mainly on 2H has revised (upward revision)

- HPC-related including Gen.AI： Sales/profits contribution to rise (approximately to Mid-40%)
- Global OSAT：Shipments of probers not limited to HPC but other Logics to increase
- China Demands：Maintain firm demand driven by high-end use
- Memory (Non-HBM)：Shipments for DRAM/NAND to increase

Metr.： Increase YoY amid recover in industry, price revision, and businesses among aerospace, defense and semis

Profits：Although pressures from an increase of various costs including from a manufacturing volume increase remain, aim to move closer to MTP target through high-value products and other factors

Order Trend

SPE： 1H order environment is very strong. 2H quantitative plan is not yet finalized; order level be on par with that of 1H

- HPC-related including Gen.AI : Except increase HoH mainly driven by Logic-related business
- Global OSAT：Inquiries likely to increase
- China Demands： Solid demand remains mainly for high-end use
- Memory (Non-HBM)： Expect acceleration toward DRAM/NAND investments

Metr.：Except an increasing opportunities among in aerospace, defense, AI infrastructures, semis, and also from subsidy-related business

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FY2027/3 Forecast

The forecast disclosed on May 13th, 2026, has been revised mainly for 2H (upward revision for both SPE and Metrology)
Forex assumption remains unchanged : ¥150 / US$ (Forex impact is minimal: High ratio of Yen-based businesses)
Per share dividend projection has also been updated following forecast revision

Company-Wide results (BJPY)	FY2026/3 1H	2H	Full Year	FY2027/3 1H(f)	2H(f)	Full Year	Changes	YoY
Orders	80.6	82.5	163.1	-	-	-		-
Sales	77.1	89.8	166.8	**88.5**	**100.5**	**189.0**	+7.5	+13%
Operating profit	14.7	19.0	33.7	**19.1**	**24.9**	**44.0**	+4.0	+30%
(OP Margin)	(19%)	(21%)	(20%)	**(22%)**	**(25%)**	**(23%)**	+1pt	+3pt
Recurring profit	15.0	19.9	34.8	**19.1**	**24.9**	**44.0**	+4.0	+26%
Net profit	9.6	15.1	24.7	**13.4**	**17.4**	**30.8**	+2.8	+24%
R&D	5.5	6.5	12.0	-	-	**13.0**	±0.0	+8%
Capex	6.9	4.2	11.1	-	-	**15.0**	+4.0	+36%
Depreciation	2.7	2.9	5.6	-	-	**6.2**	±0.0	+11%
Segment Sales	**FY2026/3 1H**	**2H**	**Full Year**	**FY2027/3 1H(f)**	**2H(f)**	**Full Year**	**Changes**	**YoY**
SPE	59.4	68.5	127.9	**69.5**	**78.0**	**147.5**	+6.0	+15%
Metr.	17.7	21.3	39.0	**19.0**	**22.5**	**41.5**	+1.5	+7%
Dividend per share (JPY)	111	151	262	**152**	**152**	**304**	+28	+42

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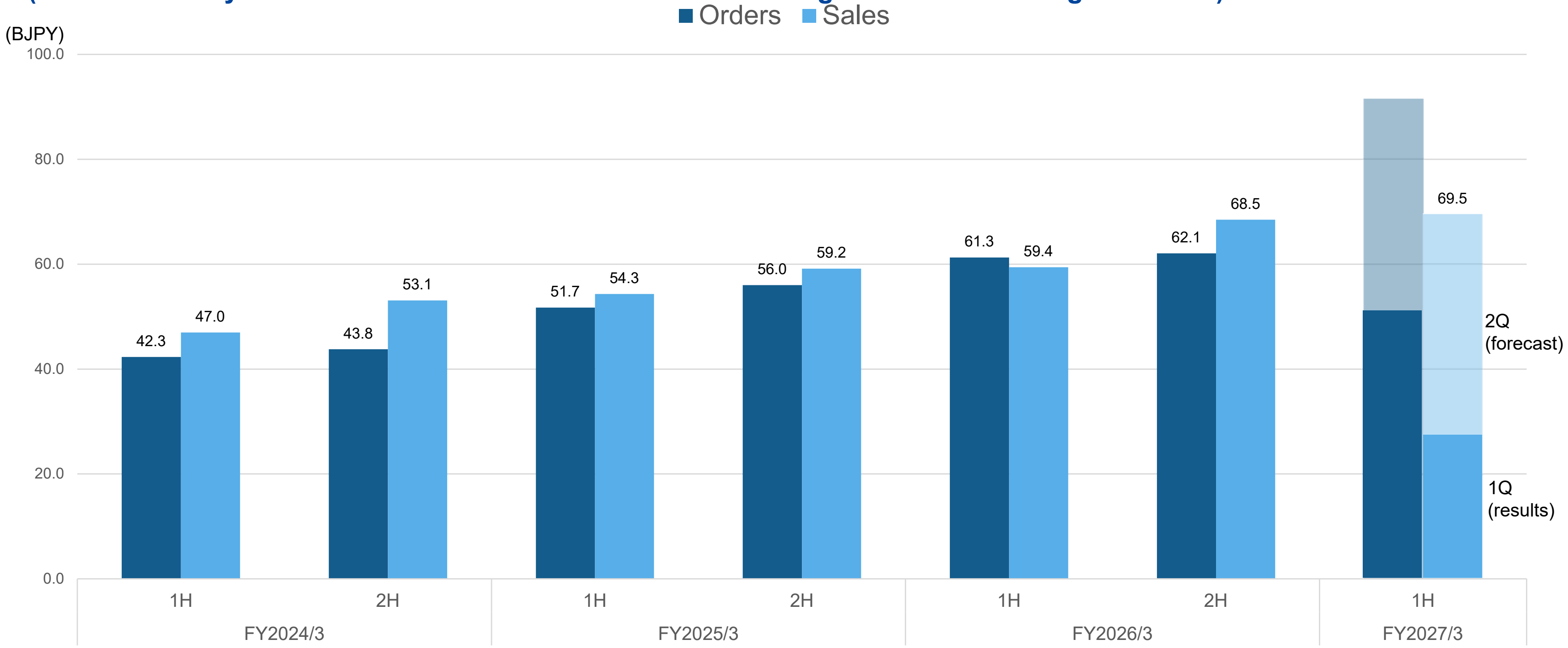
SPE Sales/Orders incl. Forecasts

FY2027/3 1H order forecast has been updated from approx. +20% HoH to approx. +50% HoH
(2Q orders likely to show a QoQ decrease as some orders might have been brought forward)



Metrology Sales/Orders incl. Forecasts

FY2027/3 1H orders are expected to increase by approximately 10% HoH

質疑応答 / Q&A

Supplementary Data - 生成AIを含むHPC / HPC-related business incl. Gen.AI

<売上高/Sales>

(前半期比増減率 / HoH Changes)	2025年度上期 FY2026/3 1H	2025年度下期 FY2026/3 2H	2026年度上期予 FY2027/3 1H (f)
生成AIを含むHPC 全体 HPC-related incl. Gen. AI	前半期比 +55% HoH	前半期比 +32% HoH	前半期比 +29% HoH
うちロジック (生成AIを含む) of which Logic (incl. Gen AI)	前半期比 +81% HoH	前半期比 +11% HoH	前半期比 +78% HoH
うちHBM of which HBM	前半期比 +28% HoH	前半期比 +64% HoH	前半期比 -15% HoH
SPE売上高に占めるHPC関連の割合 HPC-related proportion of total SPE sales	30%強 / Low 30%	30%半ば / Mid-30%	40%半ば / Mid 40%

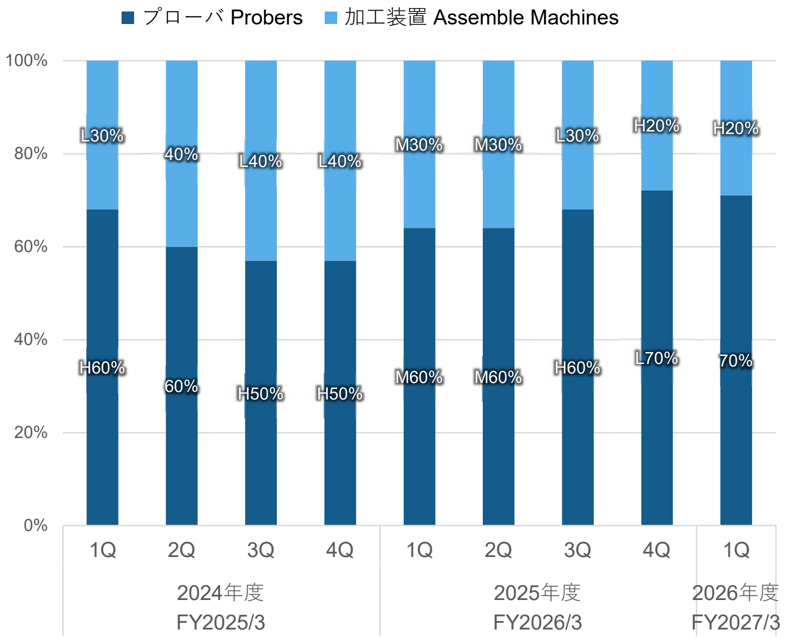
<受注高/Orders>

(前半期比増減率 / HoH Changes)	2025年度上期 FY2026/3 1H	2025年度下期 FY2026/3 2H	2026年度上期予 FY2027/3 1H (f)
生成AIを含むHPC 全体 HPC-related incl. Gen. AI	前半期比 +24% HoH	前半期比 +4% HoH	前半期比 +56% HoH
うちロジック (生成AIを含む) (*) of which Logic (incl. Gen AI) (*)	前半期比 -11% HoH	前半期比 +84% HoH	前半期比 +50% HoH
うちHBM of which HBM	前半期比 +65% HoH	前半期比 -48% HoH	前半期比 +68% HoH
SPE受注高に占めるHPC関連の割合 HPC-related proportion of total SPE orders	40%	40%	40%強 / Low 40%

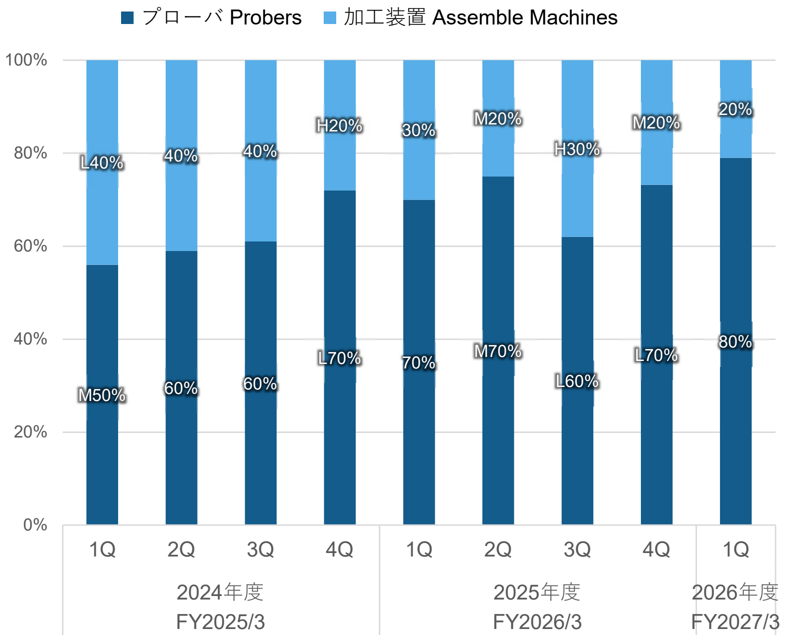
- 変動が大きいため、四半期別の開示は行っておりません。 Due to significant volatilities, the Company does not provide quarterly forecasts.
- 『生成AIを含むHPC全体』は、「うちロジック(生成AIを含む)」および「うちHBM」の合計です。「うちロジック(生成AIを含む)」には、ロジックデバイス向けプローバやAIパッケージング向けの加工装置の需要が含まれています。なお、当社は製品の特性上、検査や加工がおこなわれる半導体デバイスの種別を特定することが困難であることから、生成AIに限定した分類は行っておりません。"HPC-related incl. Gen.AI" represents the sum of 'of which Logic (incl. Gen.AI)' and 'of which HBM'. The 'of which Logic (incl. Gen. AI)' encompasses businesses for probers for logic devices and assembly equipment for AI packaging. Note that due to the nature of our products, it is difficult to identify the specific types of semiconductor devices undergoing inspection or processing; consequently, the Company does not undertake classification limited solely to Generative AI.

Supplementary Data - 製品別構成比 半導体 / SPE Segment per Product

<売上高　Sales>



<受注高　Orders>



備考：表中の記載は、L:Low(前半), M:Middle(半ば), H:High(後半)を、LSD％：一桁%前半 (0-3%) 、MSD% :一桁%半ば (4-6%)、HSD%:一桁%後半 (7-9%)を示します。内訳の合計が100%にならない場合があります。
Note: The entries in the table represent L: Low, M: Middle, and H: High; LSD%: Low Single Digit % (0-3%), MSD%: Mid Single Digit % (4–6%), and HSD%: High Single Digit % (7–9%), respectively. SUM may not equal 100%.

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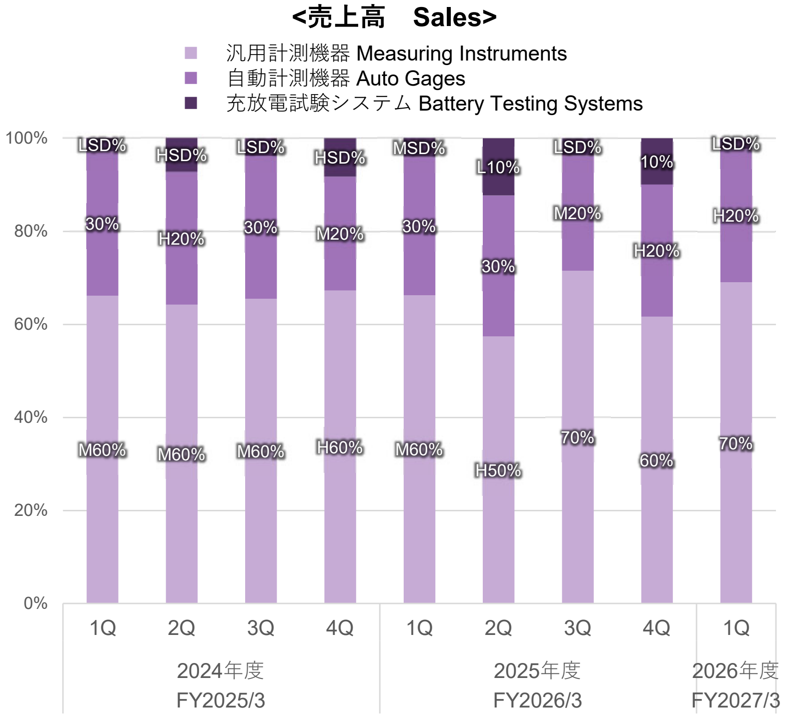
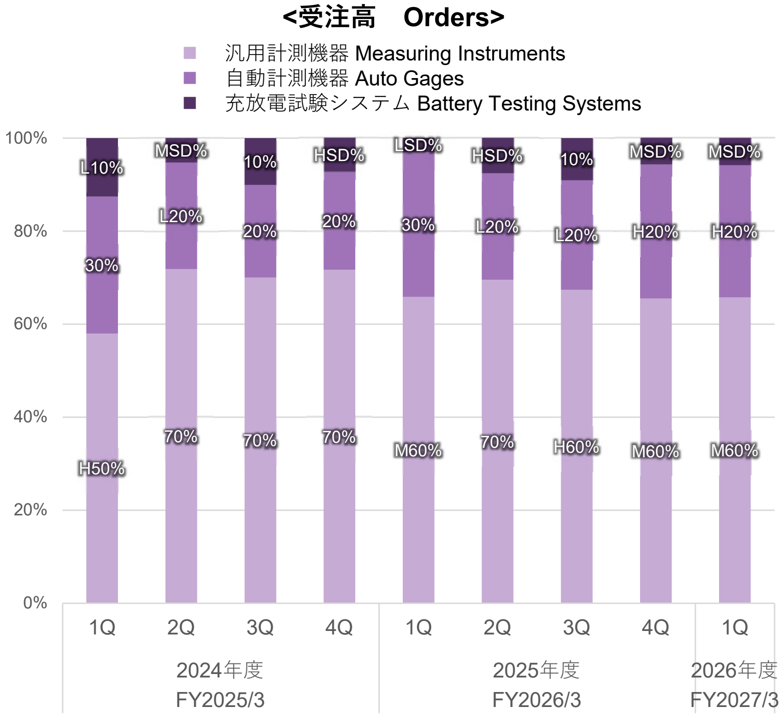
Supplementary Data - 製品別構成比 計測 / Metrology Segment per Product





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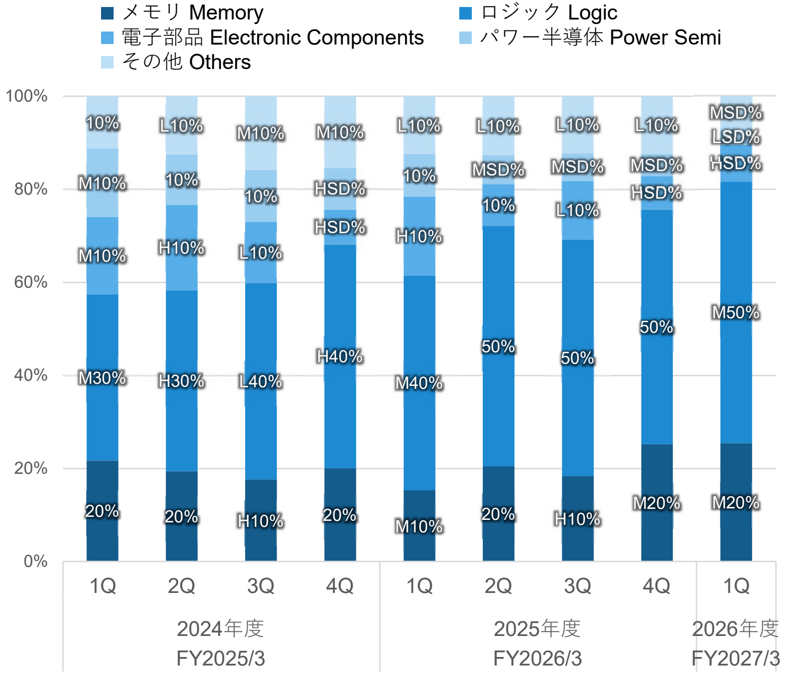
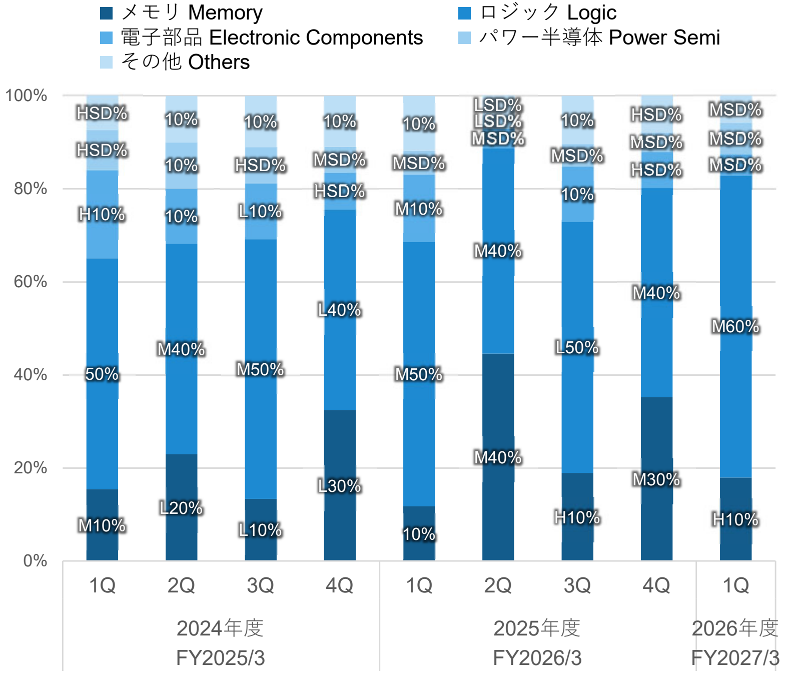
Supplementary Data - アプリ別構成比 半導体 / SPE Segment per Application

<売上高　Sales>



<受注高　Orders>



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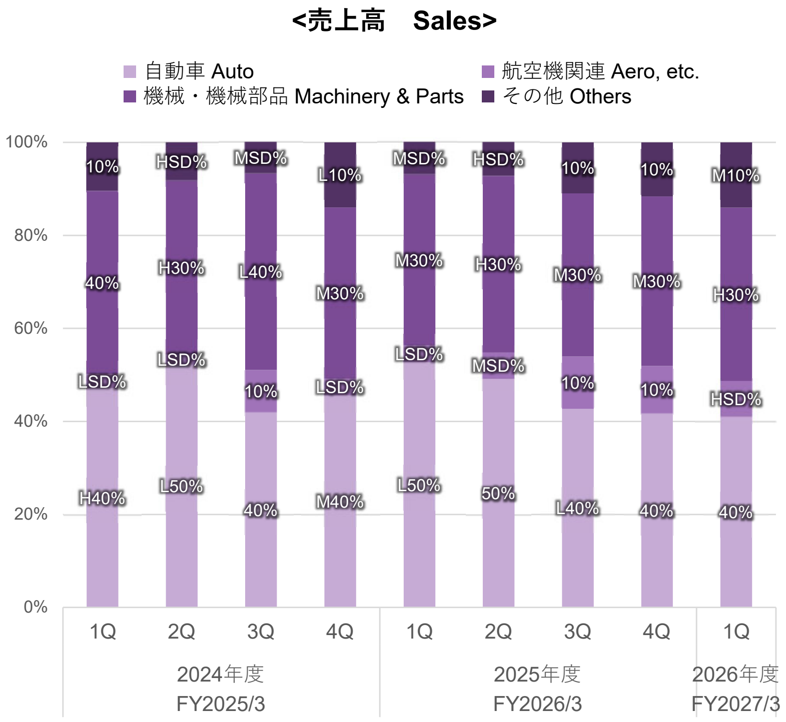
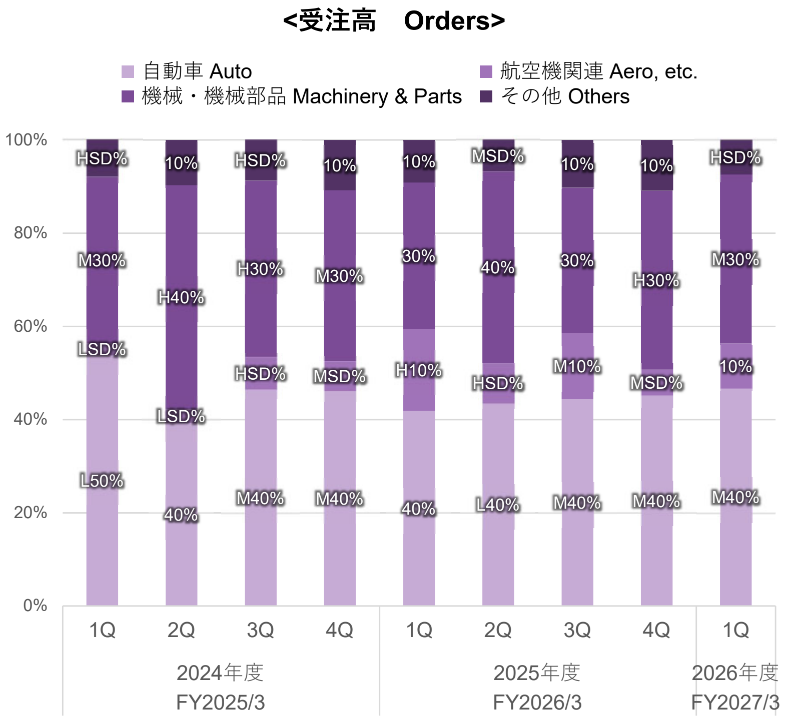
Supplementary Data - アプリ別構成比 計測 / Metrology Segment per Application





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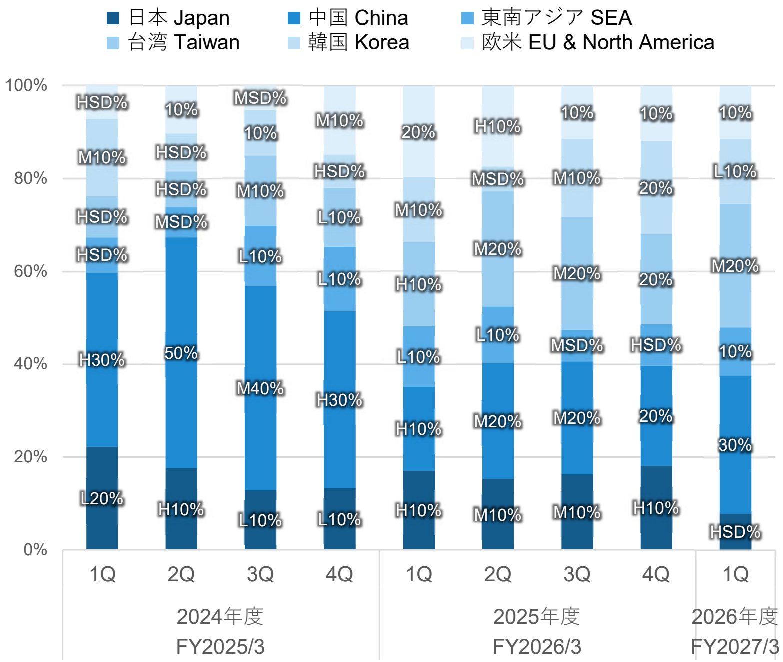
Supplementary Data - 地域別構成比 半導体 / SPE per Region

<売上高　Sales>



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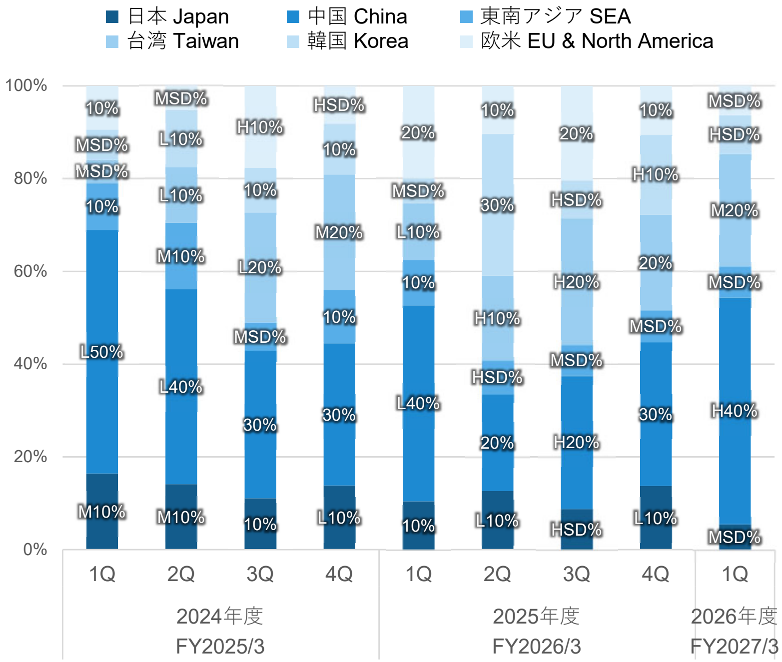

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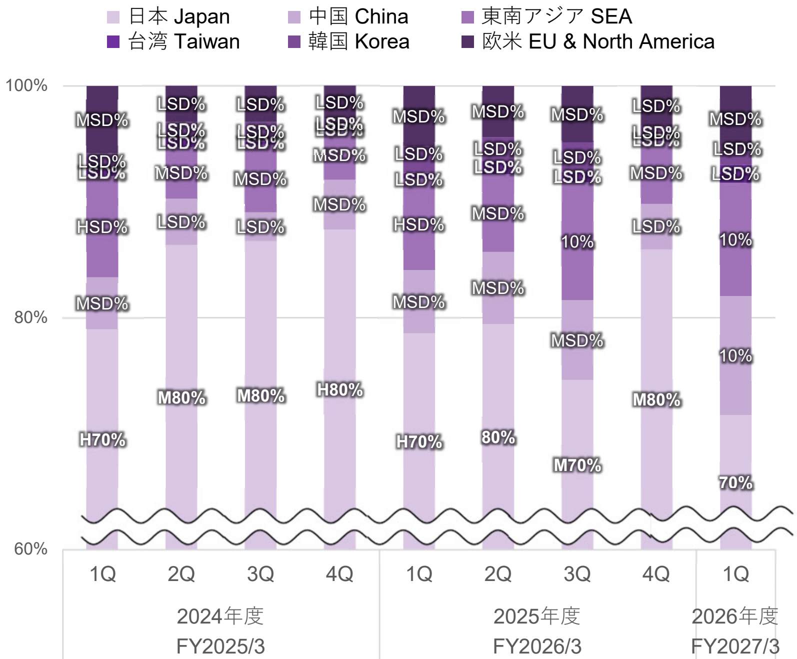
Supplementary Data - 地域別構成比 計測 / Metrology per Region

<売上高　Sales>



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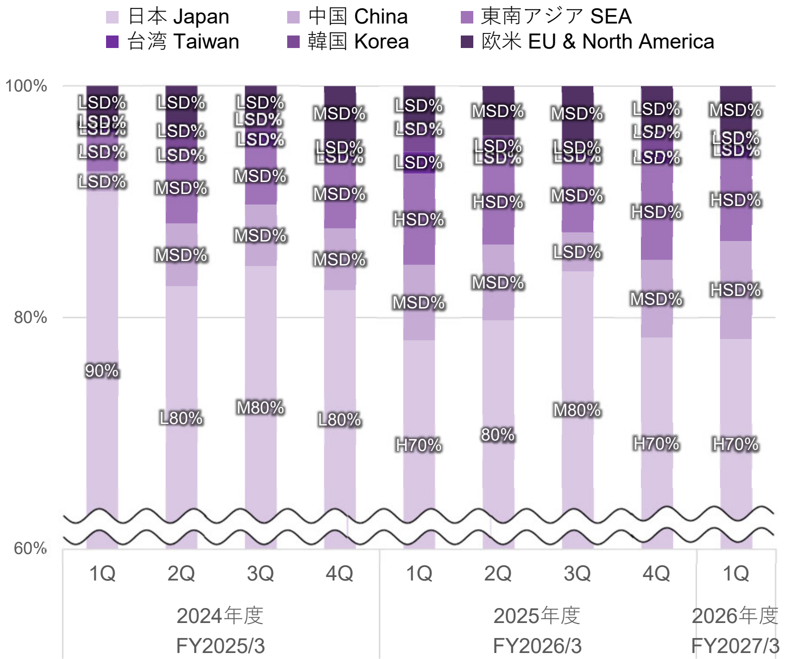

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備考：取引顧客の国籍による分類であり、日本向け売上高・受注高には第3国への輸出案件が含まれています。This data classifies based on customers' nationality. Sales and orders for Japan include export transactions to third countries.

Supplementary Data - セグメント別業績推移 / Segment

(百万円) Million Yen		連結会計期間 Consolidated Fiscal Year				四半期 Quarterly							
						2026年3月期 FY2026/3				2027年3月期 FY2027/3			
		2023年 3月期 FY2023/3	2024年 3月期 FY2024/3	2025年 3月期 FY2025/3	2026年 3月期 FY2026/3	1Q	2Q	3Q	4Q	1Q	2Q	3Q	4Q
受注高 Orders	半導体 SPE	99,366	86,082	107,713	123,396	26,378	34,945	25,965	36,106	53,236			
	計測 Metr.	36,960	34,802	37,917	39,700	9,523	9,786	10,661	9,728	12,583			
	合計 Total	136,326	120,885	145,631	163,096	35,901	44,732	36,627	45,835	65,820			
受注残高 Backlog	半導体 SPE	89,371	75,398	69,630	65,149	72,466	71,541	70,134	65,149	89,870			
	計測 Metr.	12,428	12,606	13,470	14,210	15,660	15,123	17,257	14,210	18,592			
	合計 Total	101,799	88,004	83,101	79,359	88,127	86,664	87,391	79,359	108,463			
売上高 Sales	半導体 SPE	112,365	100,055	113,481	127,878	23,542	35,870	27,372	41,092	28,515			
	計測 Metr.	34,436	34,624	37,053	38,960	7,333	10,323	8,528	12,775	8,201			
	合計 Total	146,801	134,680	150,534	166,839	30,876	46,194	35,900	53,867	36,716			
営業利益 OP	半導体 SPE	29,866	19,899	24,311	28,404	4,031	8,297	5,347	10,727	5,409			
	計測 Metr.	4,628	5,408	5,392	5,333	549	1,838	867	2,077	511			
	合計 Total	34,494	25,307	29,703	33,738	4,581	10,136	6,214	12,805	5,920			
営業利益率 OP Margin	半導体 SPE	26.6%	19.9%	21.4%	22.2%	17.1%	23.1%	19.5%	26.1%	19.0%			
	計測 Metr.	13.4%	15.6%	14.6%	13.7%	7.5%	17.8%	10.2%	16.3%	6.2%			
	合計 Total	23.5%	18.8%	19.7%	20.2%	14.8%	21.9%	17.3%	23.8%	16.1%			

Supplementary Data - 損益計算書 / Income Statement

(百万円 (EPS除く)) Million Yen(excl. EPS)	連結会計期間 Consolidated Fiscal Year				四半期 Quarterly							
					2026年3月期 FY2026/3				2027年3月期 FY2027/3			
	2023年3月期 FY2023/3	2024年3月期 FY2024/3	2025年3月期 FY2025/3	2026年3月期 FY2026/3	1Q	2Q	3Q	4Q	1Q	2Q	3Q	4Q
売上高 Net Sales	146,801	134,680	150,534	166,839	30,876	46,194	35,900	53,867	36,716			
売上原価 Cost of goods sold	84,967	79,917	88,081	97,978	18,468	27,411	21,063	31,034	21,316			
売上総利益 Gross Profit on Sales	61,834	54,762	62,453	68,860	12,407	18,783	14,837	22,832	15,400			
販売費および一般管理費 Selling, general and administrative expenses	27,339	29,454	32,750	35,122	7,825	8,647	8,622	10,026	9,479			
営業利益 Operating profit	34,494	25,307	29,703	33,738	4,581	10,136	6,214	12,805	5,920			
営業外収益 Non-operating income	965	1,404	921	1,481	133	309	609	428	576			
営業外費用 Non-operating expenses	162	259	684	394	252	-69	84	126	66			
経常利益 Recurring Profit	35,297	26,453	29,939	34,825	4,462	10,515	6,739	13,108	6,430			
特別利益 Extraordinary gains	103	824	4,493	194	3	85	105	0	3			
特別損失 Extraordinary losses	2,099	21	158	1,833	-	2,103	-	-269	-			
税金等調整前当期/四半期純利益 Profit before income taxes and minority interests	33,301	27,255	34,275	33,186	4,465	8,498	6,844	13,377	6,434			
法人税等合計 Total Income tax and others	9,607	7,791	8,531	8,354	1,228	2,090	2,268	2,768	1,698			
非支配株主に帰属する当期/四半期純利益 Net Profit attributable to minority interests	62	84	106	92	7	25	39	18	67			
親会社株主に帰属する当期/四半期純利益 Net Profit attributable to Owners of the Parent	23,630	19,378	25,637	24,739	3,229	6,382	4,536	10,590	4,667			
1株当たり当期/四半期純利益(円) Net Profit per Share(Yen)	581.33	480.49	633.75	610.02	79.77	157.32	112.74	260.73	115.01			
潜在株式調整後 1株当たり当期/四半期純利益(円) Net Profit per Share(diluted)(Yen)	575.62	475.42	628.31	606.14	-	-	-	-	-			

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Supplementary Data - 貸借対照表 / Balance Sheet

(百万円)(Million Yen)		2024年3月期 FY2024/3	2025年3月期 FY2025/3	2026年3月期 FY2026/3	2027年3月期 第1四半期 FY2027/3 1Q
流動資産 Current Assets	現金及び預金 Cash and cash equivalents	36,782	54,541	53,073	59,925
	売上債権※1 Accounts Receivable※1	42,801	39,809	47,877	39,355
	棚卸資産　Inventories	67,225	69,513	68,022	73,017
	その他　Others	7,022	5,477	5,634	2,259
	合計　Total	153,831	169,341	174,607	174,558
固定資産合計　Total Fixed Assets		71,693	68,610	75,925	76,973
総資産　Total Assets		225,524	237,952	250,533	251,531
流動負債 Current Liabilities	買入債務※2　Accounts Payable※2	17,845	16,665	17,529	18,651
	その他　Others	28,156	30,268	30,350	32,490
	合計　Total	46,002	46,933	47,879	51,141
固定負債合計　Total long-term liabilities		21,094	14,789	9,737	8,330
負債合計　Total Liabilities		67,097	61,723	57,617	59,472
純資産合計　Total Net Assets		158,427	176,229	192,916	192,058
負債・純資産合計　Total Liabilities and Net Assets		225,524	237,952	250,533	251,531
有利子負債合計　Total interest-bearing debt		25,171	20,084	14,713	13,181
自己資本比率　Equity Ratio(%)		69.4%	73.2%	76.3%	75.6%
自己資本利益率　ROE(%)		12.9%	15.5%	13.5%	-

※1: 電子記録債権、契約資産を含みます。 Incl. Electronically recorded monetary claims.
※2: 電子記録債務を含みます。 Incl. Electronically recorded obligations-operating.

Supplementary Data - 各種費用, キャッシュフロー/ Expenses and

(百万円)(Million Yen)	2024年3月期 FY2024/3	2025年3月期 FY2025/3	2026年3月期 FY2026/3	2027年3月期 第1四半期 FY2027/3 1Q
研究開発費　R&D expenses	9,042	10,354	12,037	3,333
設備投資　Capex	11,602	10,245	11,069	1,930
減価償却費（のれんの償却を除く） Depreciation（excl. Amortization of goodwill）	4,673	5,105	5,582	1,437

(百万円)(Million Yen)	2024年3月期 FY2024/3	2025年3月期 FY2025/3	2026年3月期 FY2026/3
営業活動によるキャッシュフロー Cash flows from operating activities	4,892	28,824	25,012
投資活動によるキャッシュフロー Cash flows from investing activities	-10,563	2,541	-11,491
フリーキャッシュフロー Free cash flows	-5,671	31,365	13,520
財務活動によるキャッシュフロー Cash flows from financing activities	1,616	-13,991	-15,674
現金及び現金同等物に係る換算差額等 Adjustments	755	404	689
現金及び現金同等物の期末残高 Cash and cash equivalents at the end of year	36,736	54,516	53,052

(従業員) (# of Employees)	2024年3月期 FY2024/3	2025年3月期 FY2025/3	2026年3月期 FY2026/3	2027年3月期 第1四半期 FY2027/3 1Q
正社員合計　Total full-time employees	2,658	2,767	2,890	2,994
期間平均臨時従業員数 (外書) Average number of part-time employees, not included in the above figure	1,225	1,258	1,365	1,370
従業員合計 (※1)　Number of employees	3,883	4,025	4,255	4,364

※1: 従業員合計は、正社員合計人数と、期間平均臨時従業員数の単純合算です。“Number of employees” is a simple sum of the total number of regular employees and the average number of temporary employees during the period.

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